



Material Content Data Sheet



Sales Product Name				IPB180N10S4-02		Issued		19. January 2018	
MA#				MA001641060					
Package				PG-TO263-7-3		Weight*		1529.06 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.330	0.81	0.81	8064	8064	
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158		
	non noble metal	iron	7439-89-6	0.803	0.05		525		
	non noble metal	copper	7440-50-8	801.714	52.42	52.49	524317	525000	
	non noble metal	aluminium	7429-90-5	13.663	0.89	0.89	8936	8936	
wire	non noble metal	aluminium	7429-90-5	13.663	0.89	0.89	8936	8936	
encapsulation	organic material	carbon black	1333-86-4	8.603	0.56		5626		
	plastics	epoxy resin	-	94.634	6.19		61890		
	inorganic material	silicondioxide	60676-86-0	470.303	30.76	37.51	307576	375092	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8055	8055	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	176	177	
solder	non noble metal	tin	7440-31-5	0.157	0.01		102		
	noble metal	silver	7440-22-4	0.196	0.01		128		
	non noble metal	lead	7439-92-1	7.483	0.49	0.51	4894	5124	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	iron	7439-89-6	0.106	0.01		70		
	non noble metal	copper	7440-50-8	106.210	6.95	6.96	69461	69552	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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